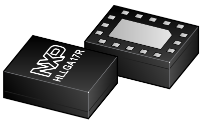


SOT1934-1

HLFLGA17, thermal enhanced low profile fine-pitch land grid array package, 17 terminals, 0.65 mm pitch, 4 mm x 3 mm x 1.348 mm body

12 July 2021

Package information

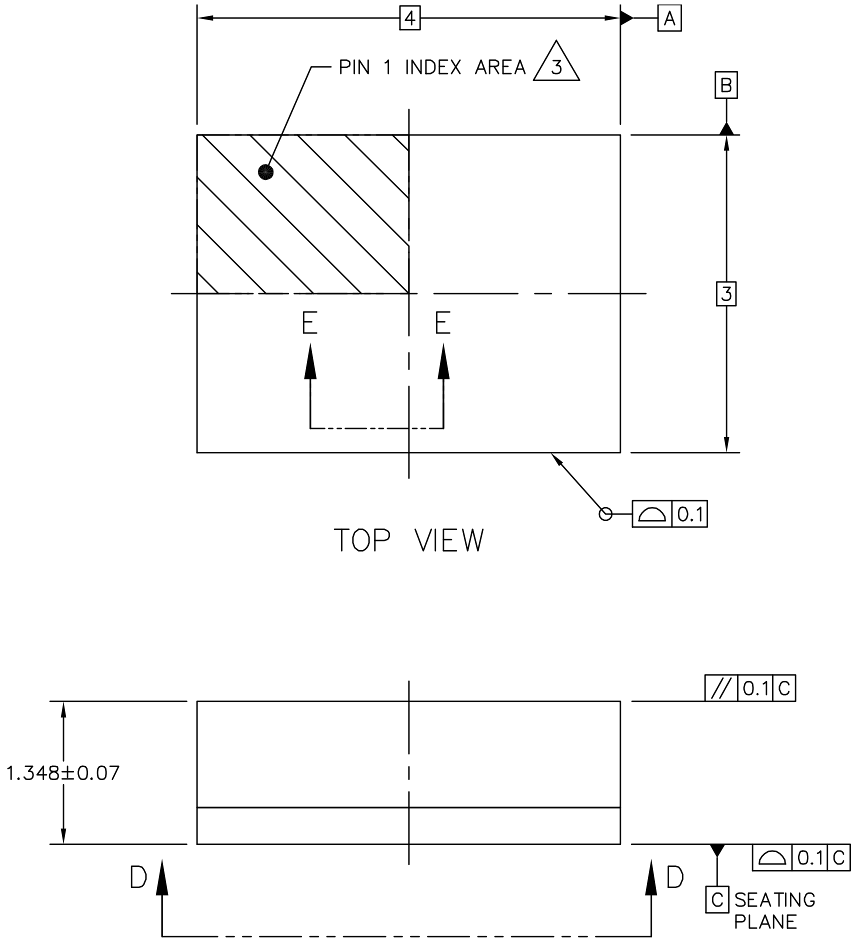
1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLFLGA17
Package style descriptive code	HLFLGA (thermal enhanced low profile fine-pitch land grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-02-2019
Manufacturer package code	98ASA01096D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	2.9	3	3.1	mm
seated height	1.341	1.348	1.355	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	17	-	

2 Package outline



RELEASED FOR EXTERNAL ASSEMBLY ONLY. THIS DESIGN ONLY MEETS EXTERNAL DESIGN AND ASSEMBLY RULES. MUST BE REVIEWED AND UPDATED BEFORE BEING ASSEMBLED INTERNALLY.

DATE: 18 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01096D	REVISION: 0	

Figure 1. Package outline HLFLGA17 (SOT1934-1)

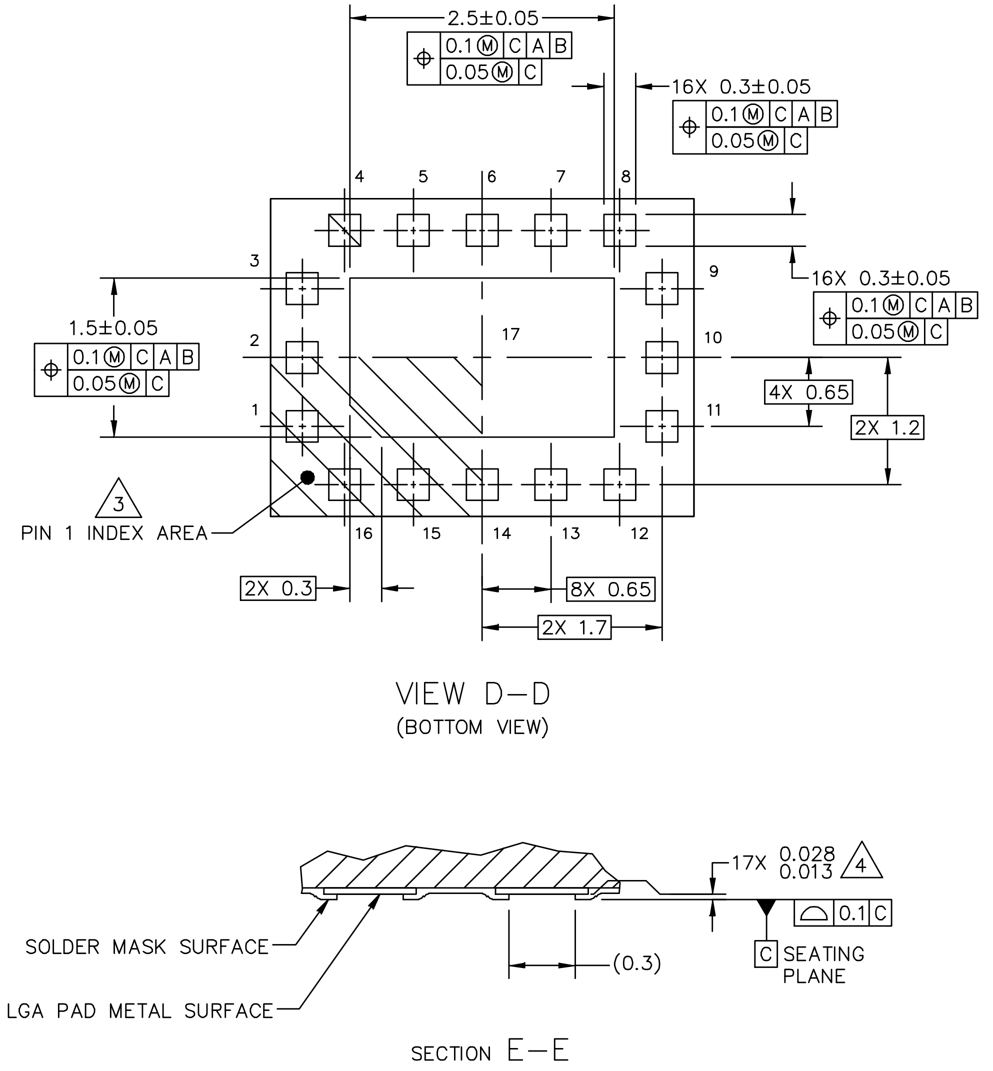


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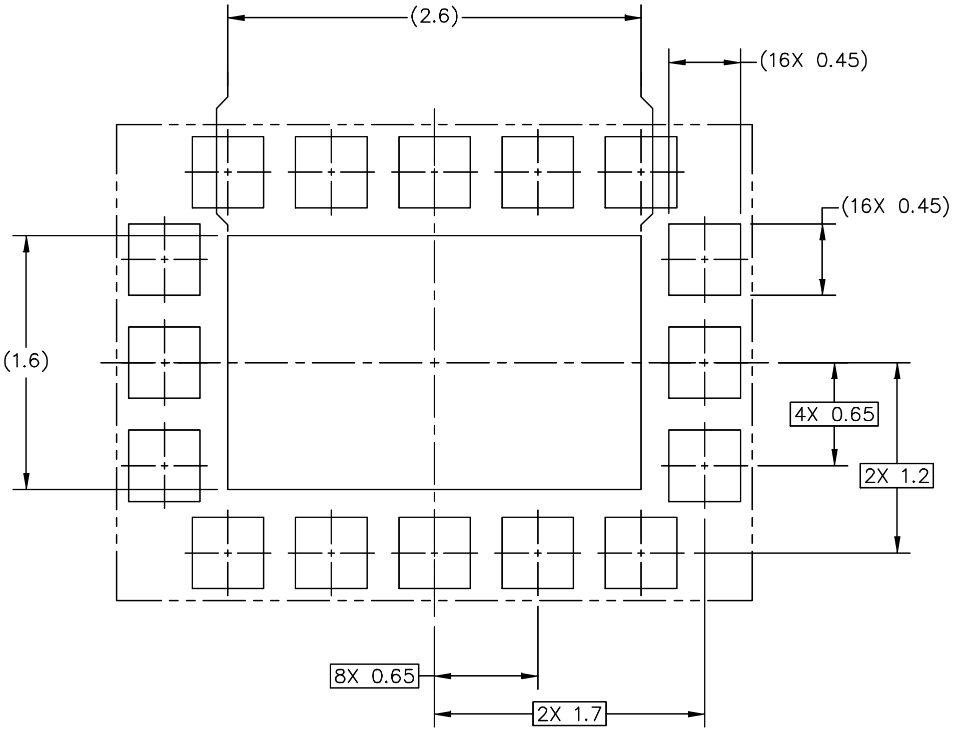
Figure 2. Package outline detail HLFLGA17 (SOT1934-1)

3 Soldering



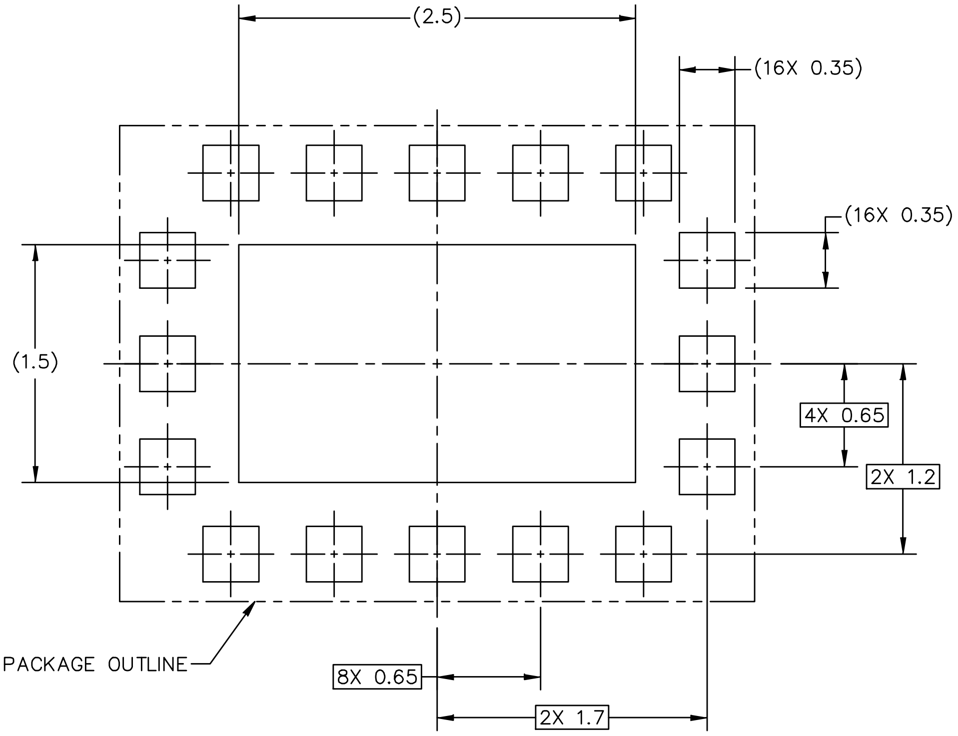
PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 18 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA01096D	REVISION: O	

Figure 3. Reflow soldering footprint part1 for HLFLGA17 (SOT1934-1)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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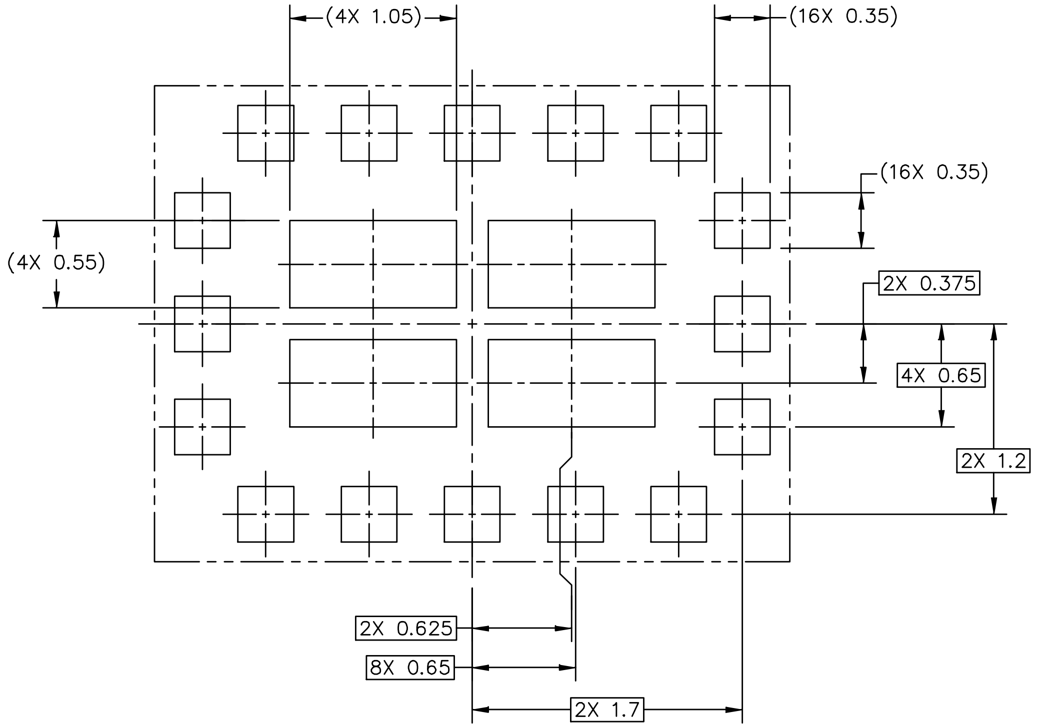
DATE: 18 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA01096D	REVISION: O	

Figure 4. Reflow soldering footprint part2 for HLFLGA17 (SOT1934-1)



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 18 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA01096D	REVISION: 0	

Figure 5. Reflow soldering footprint part3 for HLFLGA17 (SOT1934-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.

DATE: 18 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON−JEDEC	DRAWING NUMBER: 98ASA01096D	REVISION: O	

Figure 6. Package outline note HLFLGA17 (SOT1934-1)

4 Legal information

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Date of release: 12 July 2021